

REAL TIME CLOCK MODULE (SPI-Bus)

Built-in 32.768 kHz-DTCXO, +105°C operating temperature, Low current consumption, Built-in power supply switching circuit and Time stamp function up to 32 records

RX4901CE

- Built in frequency adjusted 32.768 kHz crystal unit and DTCXO
- Interface TypeCurrent consumption
- : 3 wire / 4 wire SPI-Bus

Day, date, hour, minute, second

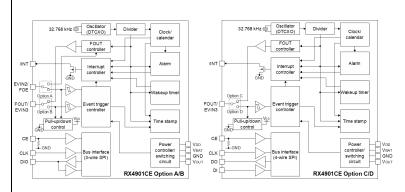
- n : 240 nA / 3 V (Typ.)
- •Auto power switching function : Automatically switches to backup power supply

: Wake up every hour or every minute or every second

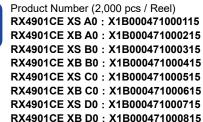
- by monitoring the VDD / VBAT voltage nction : Maximum 32 time stamps
- Time stamp function
- Interrupt output
- Alarm interruption
- Auto repeat wakeup timer interruption • Self-monitoring interruption : Crystal oscillation stop, V_{BAT} low, V_{DD} low

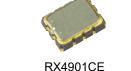
Block diagram

Din Eunetie



Pb Free RoHS Compliant





 $(3.2 \times 2.5 \text{ mm, t} = 1.0 \text{ mm Max.})$

Overview

Interface type : 3 wire / 4 wire SPI-Bus

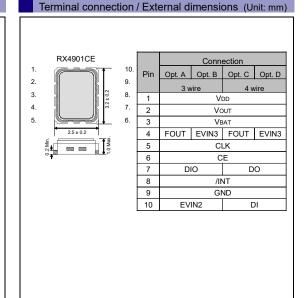
- High stability
- XS : ±3.0 x 10⁻⁶ / -40 °C to +85 °C (Monthly rate: ±8 seconds) : ±5.0 x 10⁻⁶ / +85 °C to +105 °C (Monthly rate: ±13.2 seconds)
- XB : $\pm 5.0 \times 10^{-6}$ / -40 °C to +85 °C (Monthly rate: ± 13.2 seconds)
- : ±8.0 x 10⁻⁶ / +85 °C to +105 °C (Monthly rate: ±21 seconds) • Time stamp function
- Trigger source: External event (EVIN) input, voltage drop/oscillation stop status detected, command input from the host Record data: 1/1024 seconds to 1 second, seconds, minutes, hours, days, months, years
- Number of recordable events: Maximum 32 events
- Backup power supply switching function
- The VDD and VBAT voltages are monitored to switch between Normal mode (VDD operation) and Backup mode (VBAT operation). • Clock output (FOUT)
- Selectable from 32.768 kHz, 1024 Hz and 1 Hz outputs

Output can be controlled by a register or FOE input (selectable with a register).

Pin Function							
Signal Name	I/O	Function					
EVIN1,2,3	Input	External event input pins. Detectable even in Backup mode. Pull-up and pull-down is configurable by the resisters					
CE	Input	Slave select input pin A pull-down resistor (Typ. 300 k Ω) is included					
CLK	Input	Serial clock input pin					
DI	Input	Serial data input pin (4 wire)					
DO	Output	Serial data Output pin (4 wire)					
DIO	Input / Output	Serial data input/output pin (3 wire)					
FOUT	Output	Frequency output pin (CMOS). 32.768 kHz (default), 1024 Hz or 1 Hz clock output is selectable. This pin can be switched to the wakeup timer interrupt output (CMOS)					
/INT	Output	Interrupt output pin (N-ch. open drain). The wakeup timer, time update, alarm, and/or event detection interrupt signals can be selected to output from this pin. When two or more signals are selected, they are NORed before being output. This pin is effective even in Backup mode.					
Vdd	-	Power-supply pin					
Vout	-	Internal operating voltage output pin Connect a 1.0 μF bypass capacitor to this pin.					
Vbat	-	Backup power supply pin Connect a backup power supply such as a large-size capacitor, secondary battery, or primary battery. The operating power voltage is supplied from this pin to the internal circuits in Backup mode.					
GND	-	Ground pin					

Specifications (characteristics)

Recommended Operating Conditions									
Item		Symbol	Symbol Condition N		-	Тур.		lax.	unit
Operating voltage		Vdd	-	1.6		3.0	Ę	5.5	V
Clock supply voltage		Vclk	-	1.1		3.0	5	5.5	V
Operating Temperature		Ta	-	-40		+25	+	105	°C
VDD detection voltage		-VDET1	VDD, Fall	1.35	i 1	1.45	1	.55	V
Frequency Characteristics									
Item	Symbol		Condition		Min.	Ту	γp.	Max	unit
Frequency tolerance	∆f/f	xs	Ta = -40 to +85 °C		-3		-	+3	
			Ta = -40 to +105 °C		-5	-	-	+5	× 10 ^{−6}
		ХВ	Ta = -40 to +85 °C		-5	-	-	+5	× 10 ·
			Ta = -40 to +105 °C		-8	-	-	+8	
start-up time	t STA	Ta = + VDD =	-	0	.5	1.0	s		



* Refer to application manual for details

- 40 °C to 1105 °C

Cu	Current consumption $I_a = -40 \text{ °C to } +105 \text{ °C}$								
Item	Symbol	Condition					Тур.	Max.	unit
	IBAT	VBAT = 3.0 V, /INT= Hi-Z, FC Temperature of FSEL1= FSEL CHGEN = 0, 0	-	240	1500	nA			
IDD	1 32k	VDD = 3.0 V, /INT= Hi-Z, FC Temperature of FSEL1 = FSE CHGEN = 0, 0		-	1.0	3.0	μA		
Option									
I/F	Option	EVIN pin Number	/INTpin Number	FOUT		lumber of time stamps record by EVIN terminal trigge FIFO Mode Direct Mod			Э
SPI	Α	1	1	Yes	3	32 times 12 times		nes	
3 wire	В	2	1	-	3	32 times 22 tim		nes	
SPI	C 0 1 Yes			0 time		0 tin	0 time		
wire	ire D 1 1 - 3		2 time	s	10 tin	nes			

Current consumption

3

SEIKO EPSON CORPORATION



Product name

RX4901CE	XS	A0
1	2	3

- ① Model CE type package 3.2 x 2.5 x 1.0 mm
- 2 Frequency tolerance
 - XS: ±3.0 x 10⁻⁶ / -40 °C to +85 °C (Monthly rate: ±8 seconds) ±5.0 x 10⁻⁶ / +85 °C to +105 °C (Monthly rate: ±13.2 seconds) XB: ±5.0 x 10⁻⁶ / -40 °C to +85 °C (Monthly rate: ±13.2 seconds) ±8.0 x 10⁻⁶ / +85 °C to +105 °C (Monthly rate: ±21 seconds)
- ③ Pin Option
 - A: Option A
 - B: Option B
 - C: Option C
 - D: Option D

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